IPC ASSOCIATION ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under botternational and Pan-American copyright conventions.		der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfg Information				
upplier	Information						·							
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi											2024-05-12			
Contact Na	nme	Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-E	nv-Stewards		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
uthorized	Representative*	Title - Representative			I	Phone - Representative*				Email - Representative*				
Product-E	nv-Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	ı	Manufacturing Site		Veight*	UOM	Unit Type
		NTMFS4H013NFT1G FETKY SO8FL		FETKY SO8FL 25	5V 35A 9.1MO 2		2024-05-12	24-05-12 MY1		MY1	1:		mg	Each
Ianufac	turing Proccess Inform	ation											·	
	2 7			Terminal Base Alloy J-STD-020 MSL		L Rating			re Max Time at Peak	Temperatu	ire Numb	er of Reflow Cyc	eles	
]	Matte Tin (Sn) - annealed	(CU Alloy	1			260		C	30	secono	ls 3		
omments														
vel 1 - ma	ximum time at peak tempera	ture during sol	ldering is 10-3	0 seconds										
or more i	nformation regarding materi	al composition	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier has not independently verified information provided by others, Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	4.8	mg	Supplier	Iron (Fe)	7439-89-6		0.0048	mg
			Supplier	Copper (Cu)	7440-50-8		4.7938	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0014	mg
Die	0.713	mg	Supplier	Silicon (Si)	7440-21-3		0.713	mg
Die Attach Solder	11.9	mg	Supplier	Silver (Ag)	7440-22-4		0.2975	mg
			A	Lead (Pb)	7439-92-1	7a	11.0075	mg
			Supplier	Tin (Sn)	7440-31-5		0.595	mg
Lead Frame	47.57	mg	Supplier	Silver (Ag)	7440-22-4		0.0285	mg
			Supplier	Iron (Fe)	7439-89-6		0.0476	mg
			Supplier	Copper (Cu)	7440-50-8		47.4796	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0143	mg
Mold Compound-Black	47.136	mg		Epoxy resin	proprietary data		3.5352	mg
			Supplier	Phenolic Resin	Proprietary Data		1.1784	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.5352	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2357	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		38.6515	mg
Plating	0.95	mg	Supplier	Tin (Sn)	7440-31-5		0.95	mg
Wire Bond - Au	0.1	mg	Supplier	Gold (Au)	7440-57-5		0.1	mg